

Australian/New Zealand Standard™

**Electric components — Reliability —  
Reference conditions for failure rates  
and stress models for conversion**



AS/NZS IEC 61709:2019

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## Preface

This Standard was prepared by the Joint Standards Australia/Standards New Zealand Committee QR-005, Dependability.

The objective of this Standard is to give guidance on the use of failure rate data for reliability prediction of electric components used in equipment. The method presented in this document uses the concept of reference conditions which are the typical values of stresses that are observed by components in the majority of applications. Reference conditions are useful since they provide a known standard basis from which failure rates can be modified to account for differences in environment from the environments taken as reference conditions.

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